

$V_{CE} = 600\text{ V}$, $I_C = 37\text{ A}$
Trench IGBT with Fast Recovery Diode
MGD633

Description

The MGD633 is 600 V trench IGBT. Sanken original trench structure decreases gate capacitance, and achieves high speed switching and switching loss reduction. Thus, the IGBT can improve the efficiency of your circuit.

Features

- Low Saturation Voltage
- High Speed Switching
- With Integrated Low V_F Fast Recovery Diode
- Bare Lead Frame: Pb-free (RoHS Compliant)

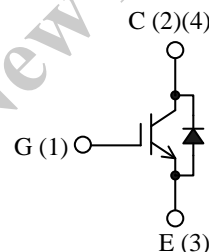
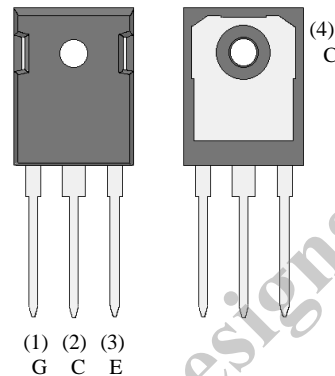
- V_{CE} ----- 600 V
- I_C ($T_C = 100\text{ }^\circ\text{C}$)----- 37 A
- $V_{CE(sat)}$ ----- 1.8 V typ.
- t_f ($T_J = 25\text{ }^\circ\text{C}$)----- 120 ns typ.
- V_F ----- 1.3 V typ.

Applications

- Microwave Oven
- IH Cooker
- Inverter Circuit

Package

TO247-3L



Not to scale

Not Recommended for New Designs

Absolute Maximum Ratings

 Unless otherwise specified, $T_A = 25\text{ }^\circ\text{C}$.

| Parameter | Symbol | Conditions | Rating | Unit | Remarks |
|------------------------------------|----------------|--|------------|------------------|---------|
| Collector to Emitter Voltage | V_{CE} | | 600 | V | |
| Gate to Emitter Voltage | V_{GE} | | ± 30 | V | |
| Continuous Collector Current | I_C | $T_C = 25\text{ }^\circ\text{C}$ | 50 | A | |
| | | $T_C = 100\text{ }^\circ\text{C}$ | 37 | A | |
| Pulsed Collector Current | $I_{C(PULSE)}$ | $P_W \leq 1\text{ ms}$, duty cycle $\leq 1\%$ | 100 | A | |
| Diode Continuous Forward Current | I_F | $T_C = 25\text{ }^\circ\text{C}$ | 40 | A | |
| Diode Pulsed Forward Current | $I_{F(PULSE)}$ | $P_W \leq 1\text{ ms}$, duty cycle $\leq 1\%$ | 100 | A | |
| Maximum Collector to Emitter dv/dt | dv/dt | $T_C \leq 125\text{ }^\circ\text{C}$, see Figure 1 | 5 | V/ns | |
| Power Dissipation | P_D | $T_C = 25\text{ }^\circ\text{C}$ | 150 | W | |
| Operating Junction Temperature | T_J | | 150 | $^\circ\text{C}$ | |
| Storage Temperature | T_{STG} | | -55 to 150 | $^\circ\text{C}$ | |

Thermal Characteristics

 Unless otherwise specified, $T_A = 25\text{ }^\circ\text{C}$.

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit | Remarks |
|---|-----------------------|------------|------|------|-------|--------------------|---------|
| Thermal Resistance of IGBT (Junction to Case) | $R_{\theta JC(IGBT)}$ | | — | — | 0.833 | $^\circ\text{C/W}$ | |
| Thermal Resistance of Diode (Junction to Case) | $R_{\theta JC(Di)}$ | | — | — | 1.67 | $^\circ\text{C/W}$ | |

Electrical Characteristics

 Unless otherwise specified, $T_A = 25\text{ }^\circ\text{C}$.

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|--|---------------|---|------|------|-----------|---------------|
| Collector to Emitter Breakdown Voltage | $V_{(BR)CES}$ | $I_C = 100\text{ }\mu\text{A}$, $V_{GE} = 0\text{ V}$ | 600 | — | — | V |
| Collector to Emitter Leakage Current | I_{CES} | $V_{CE} = 600\text{ V}$, $V_{GE} = 0\text{ V}$ | — | — | 100 | μA |
| Gate to Emitter Leakage Current | I_{GES} | $V_{GE} = \pm 30\text{ V}$ | — | — | ± 500 | nA |
| Gate Threshold Voltage | $V_{GE(TH)}$ | $V_{CE} = 10\text{ V}$, $I_C = 1\text{ mA}$ | 4 | 5.5 | 7 | V |
| Collector to Emitter Saturation Voltage | $V_{CE(sat)}$ | $V_{GE} = 15\text{ V}$, $I_C = 50\text{ A}$ | — | 1.8 | 2.4 | V |
| Input Capacitance | C_{ies} | $V_{CE} = 20\text{ V}$, $V_{GE} = 0\text{ V}$, $f = 1.0\text{ MHz}$ | — | 2500 | — | pF |
| Output Capacitance | C_{oes} | | — | 150 | — | |
| Reverse Transfer Capacitance | C_{res} | | — | 80 | — | |
| Total Gate Charge | Q_G | $V_{CE} = 300\text{ V}$ $I_C = 50\text{ A}$ $V_{GE} = 15\text{ V}$ | — | 65 | — | nC |
| Gate to Emitter Charge | Q_{GE} | | — | 20 | — | |
| Gate to Collector Charge | Q_{GC} | | — | 20 | — | |
| Turn-on Delay Time | $t_{d(on)}$ | $T_J = 25\text{ }^\circ\text{C}$, see Figure 1 | — | 75 | — | ns |
| Rise Time | t_r | | — | 100 | — | |
| Turn-off Delay Time | $t_{d(off)}$ | | — | 300 | — | |
| Fall Time | t_f | | — | 120 | — | |
| Turn-on Delay Time | $t_{d(on)}$ | $T_J = 125\text{ }^\circ\text{C}$, see Figure 1 | — | 75 | — | ns |
| Rise Time | t_r | | — | 100 | — | |
| Turn-off Delay Time | $t_{d(off)}$ | | — | 300 | — | |
| Fall Time | t_f | | — | 200 | — | |
| Emitter to Collector Diode Forward Voltage | V_F | $I_F = 40\text{ A}$ | — | 1.3 | 1.7 | V |
| Emitter to Collector Diode Reverse Recovery Time | t_{rr} | $I_F = 40\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ | — | 350 | — | ns |

Test Circuits and Waveforms

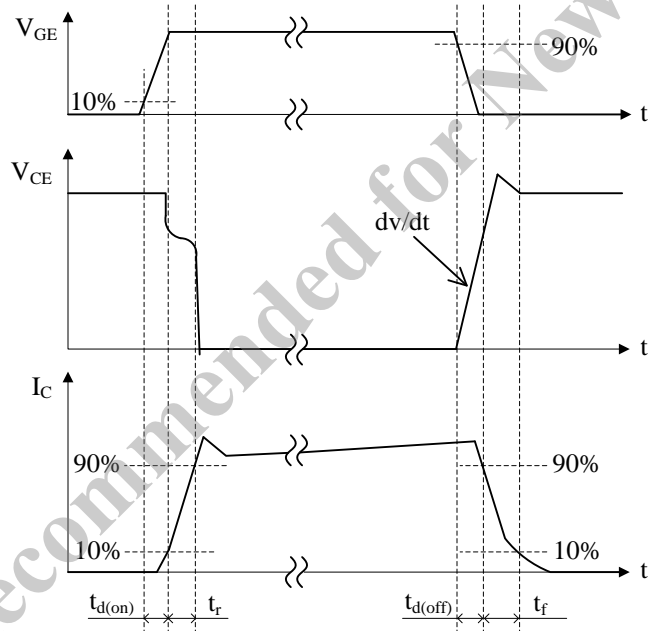
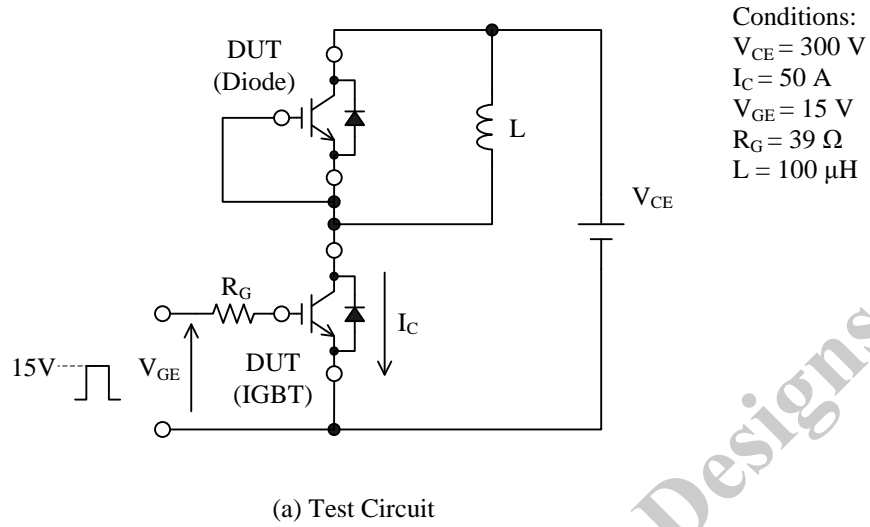


Figure 1. Test Circuits and Waveforms of dv/dt and Switching Time

Rating and Characteristic Curves

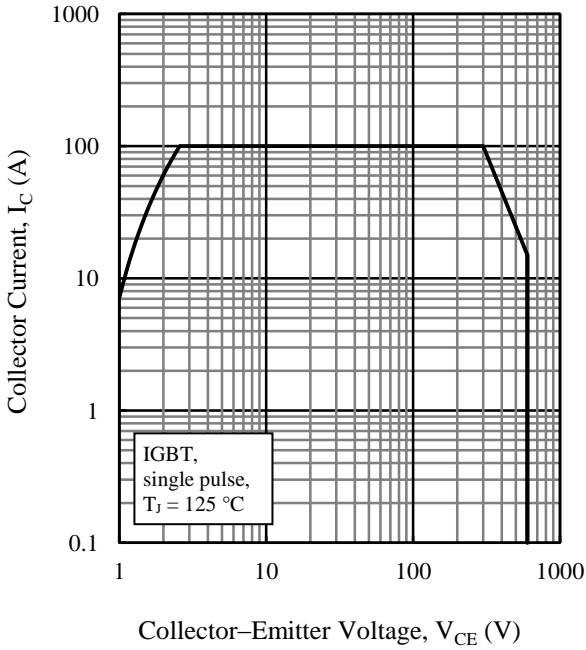


Figure 2. IGBT Reverse Bias Safe Operating Area

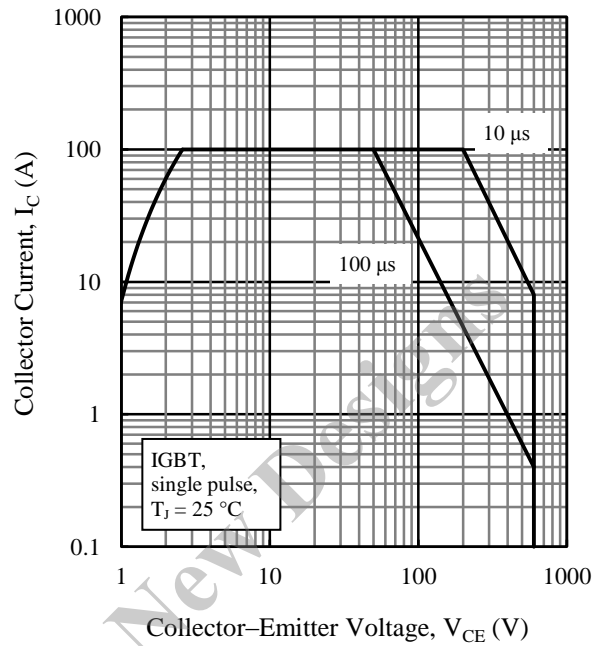


Figure 3. IGBT Safe Operating Area

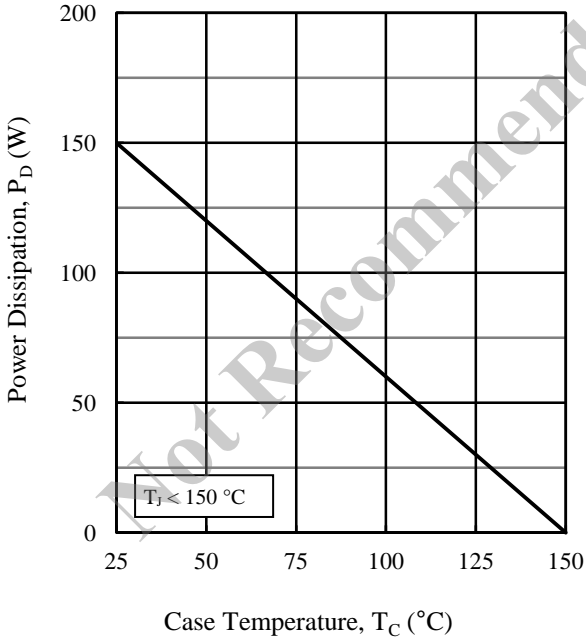


Figure 4. Power Dissipation vs. Case Temperature

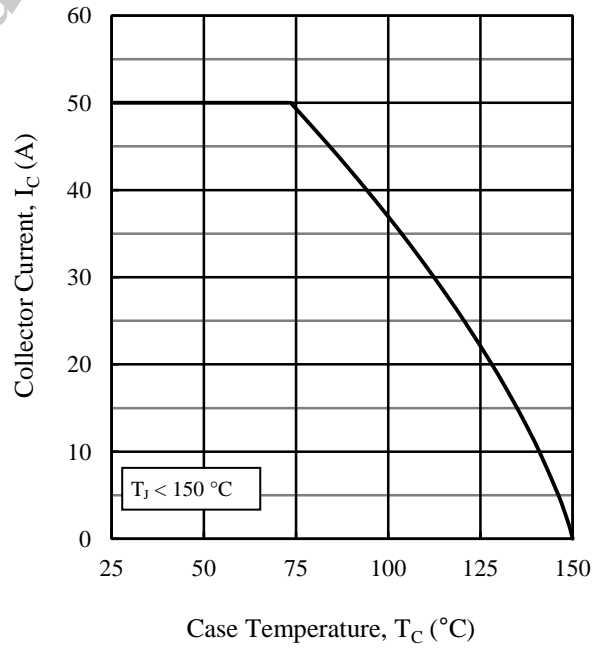


Figure 5. Collector Current vs. Case Temperature

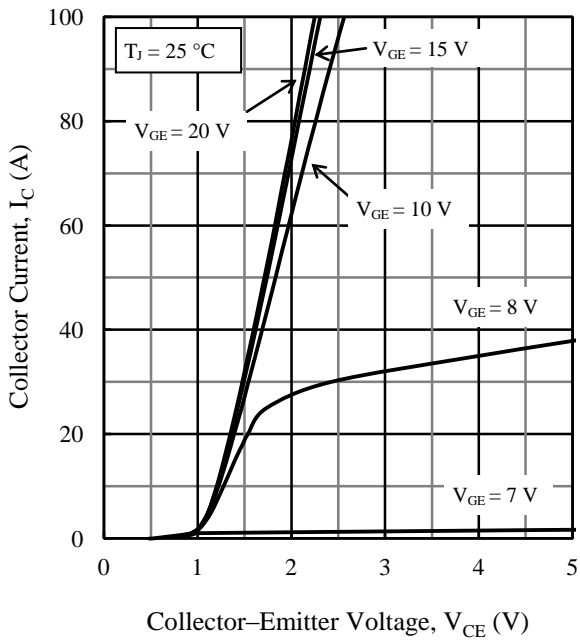


Figure 6. Output Characteristics ($T_J = 25\text{ }^\circ\text{C}$)

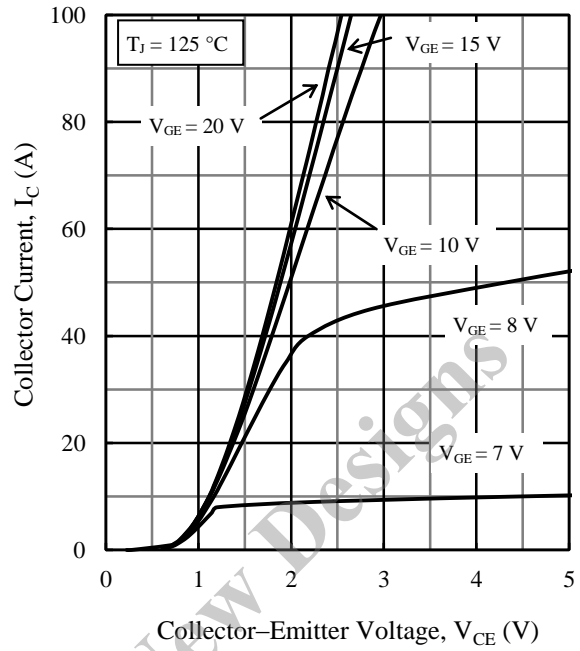


Figure 7. Output Characteristics ($T_J = 125\text{ }^\circ\text{C}$)

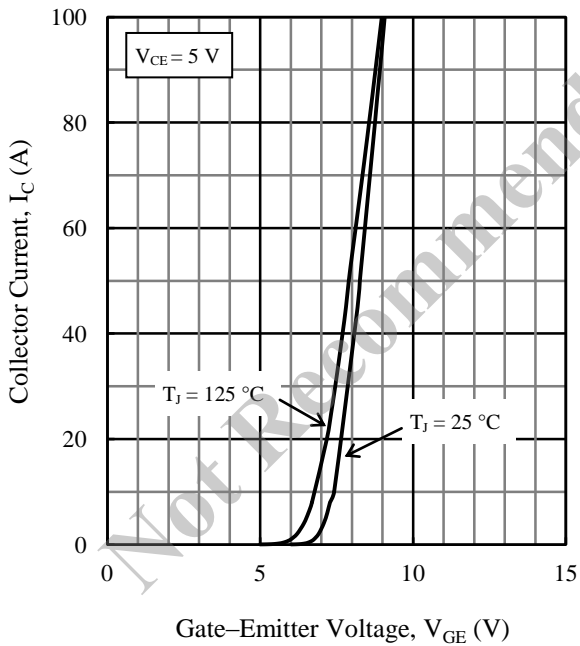


Figure 8. Transfer Characteristics

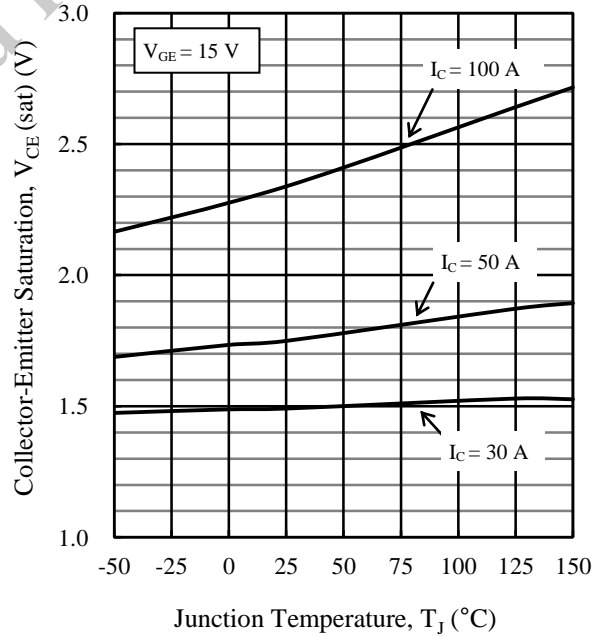


Figure 9. Saturation Voltage vs. Junction Temperature

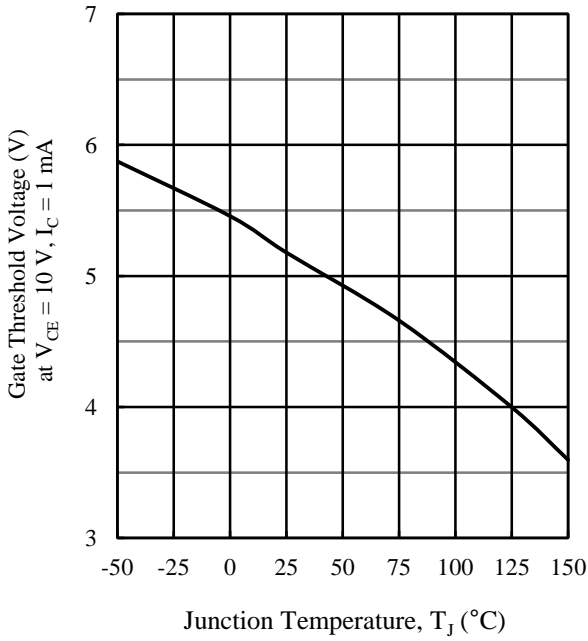


Figure 10. Gate Threshold Voltage vs. Junction Temperature

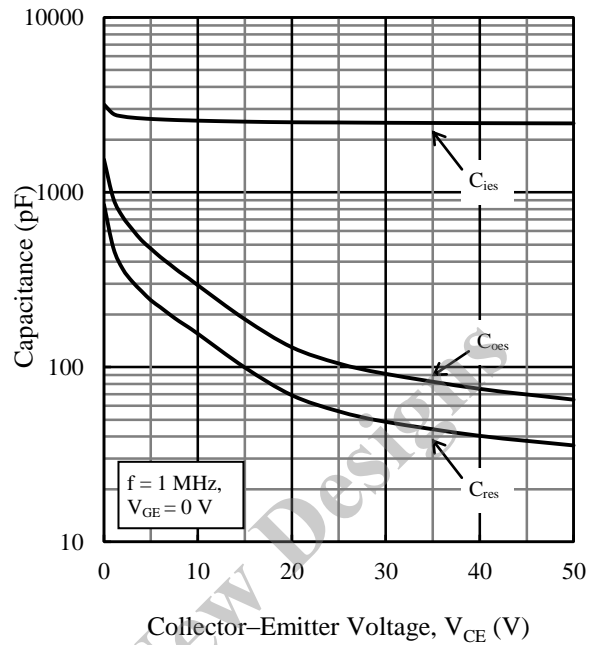


Figure 11. Capacitance Characteristics

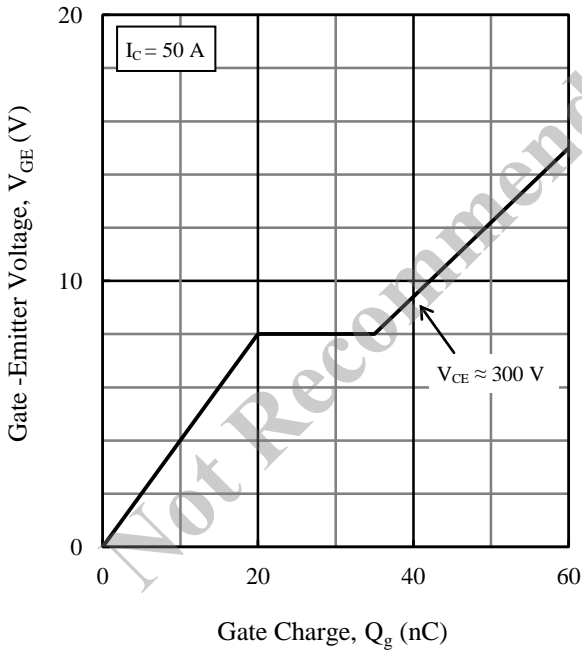


Figure 12. Typical Gate Charge

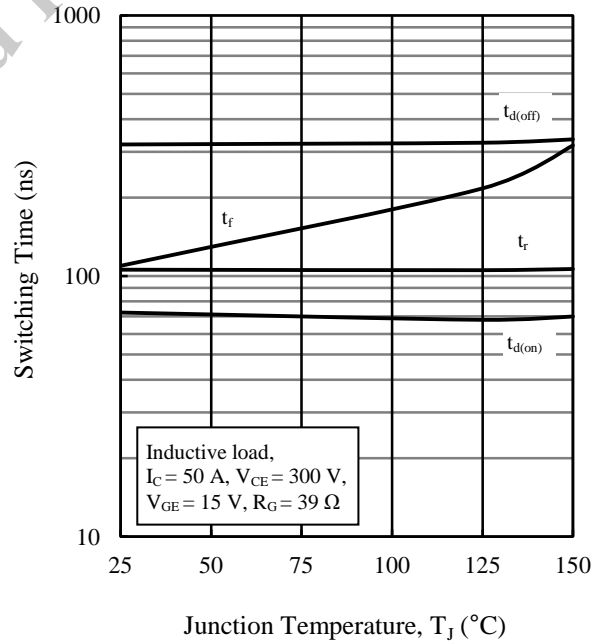


Figure 13. Switching Time vs. Junction Temperature

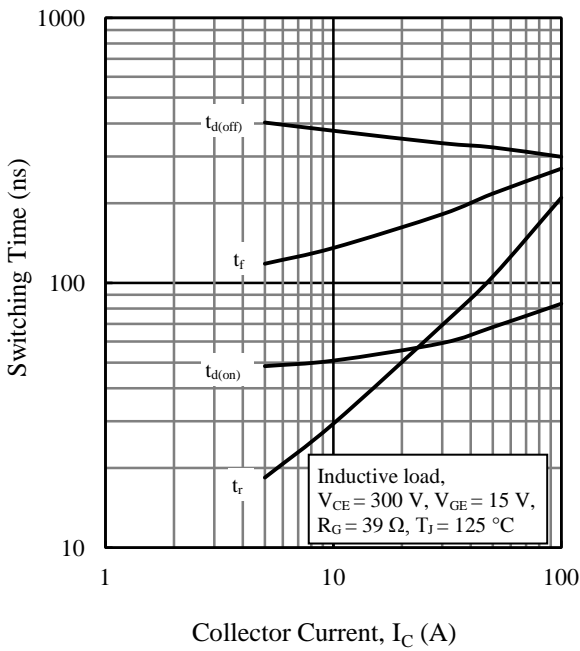


Figure 14. Switching Time vs. Collector Current

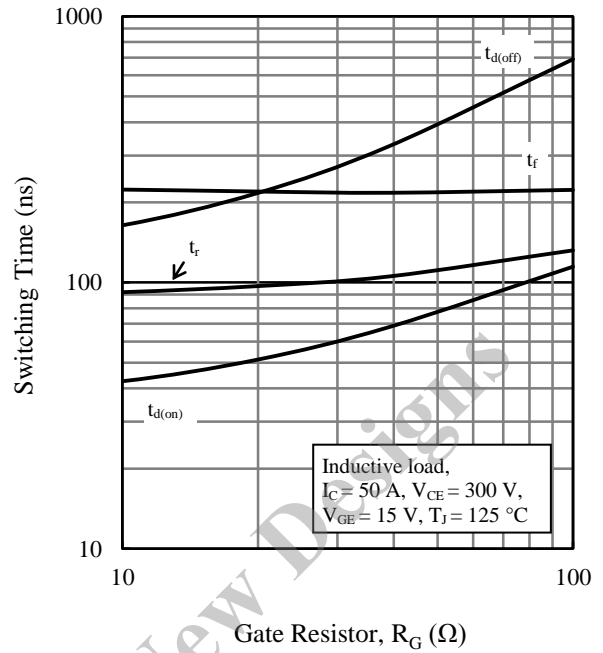


Figure 15. Switching Time vs. Gate Resistor

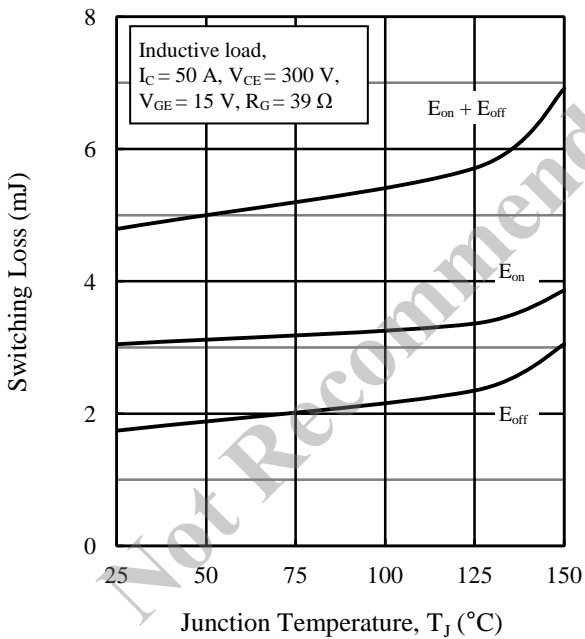


Figure 16. Switching Loss vs. Junction Temperature

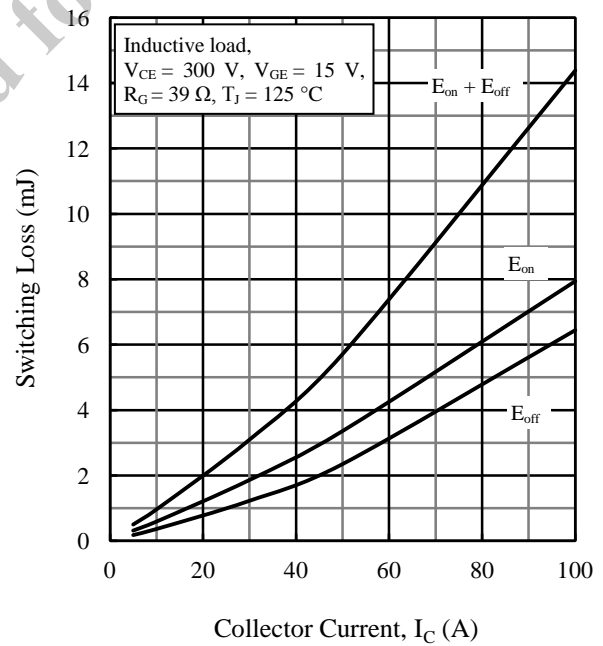


Figure 17. Switching Loss vs. Collector Current

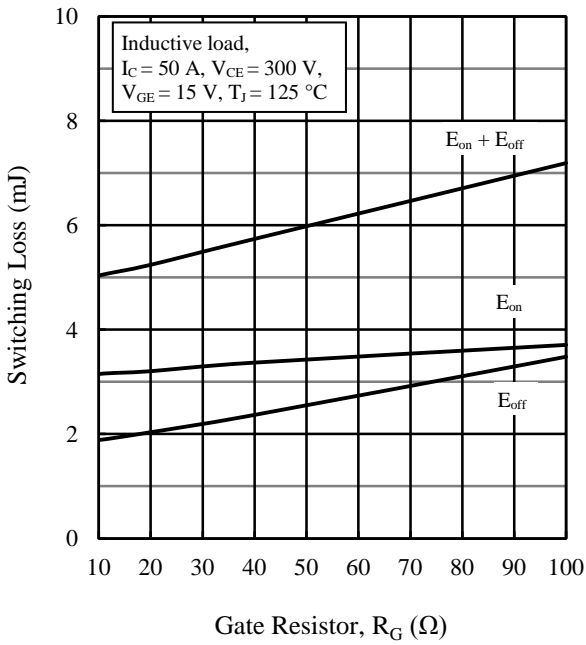


Figure 18. Switching Loss vs. Gate Resistor

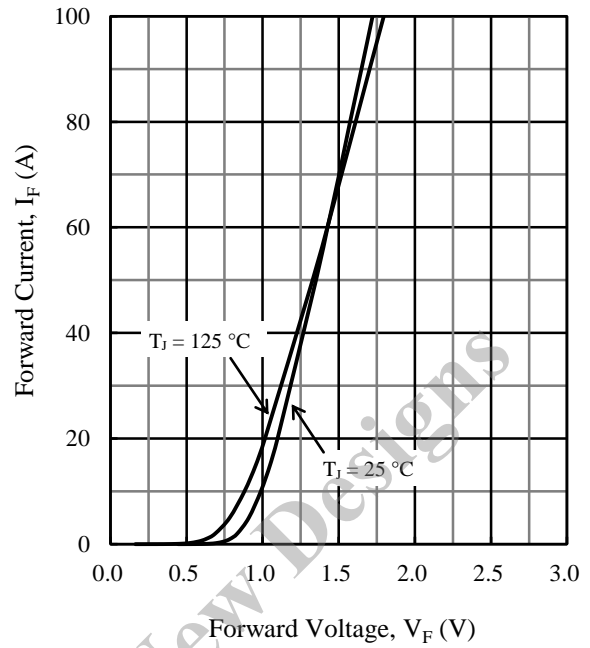


Figure 19. Diode Forward Characteristics

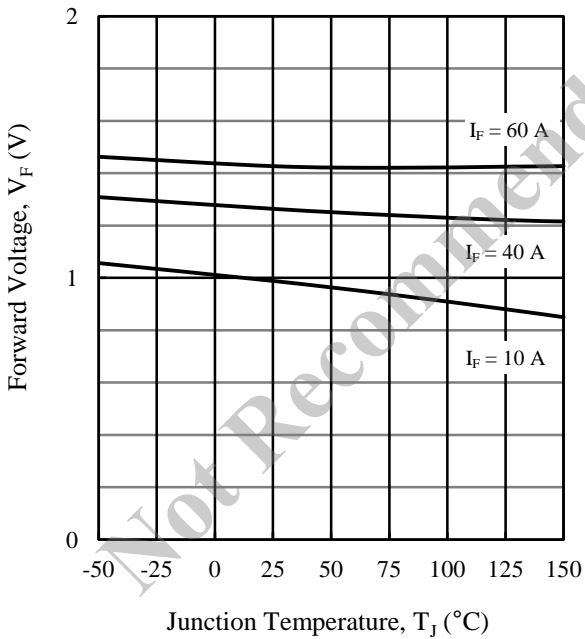


Figure 20. Diode Forward Voltage vs. Junction Temperature

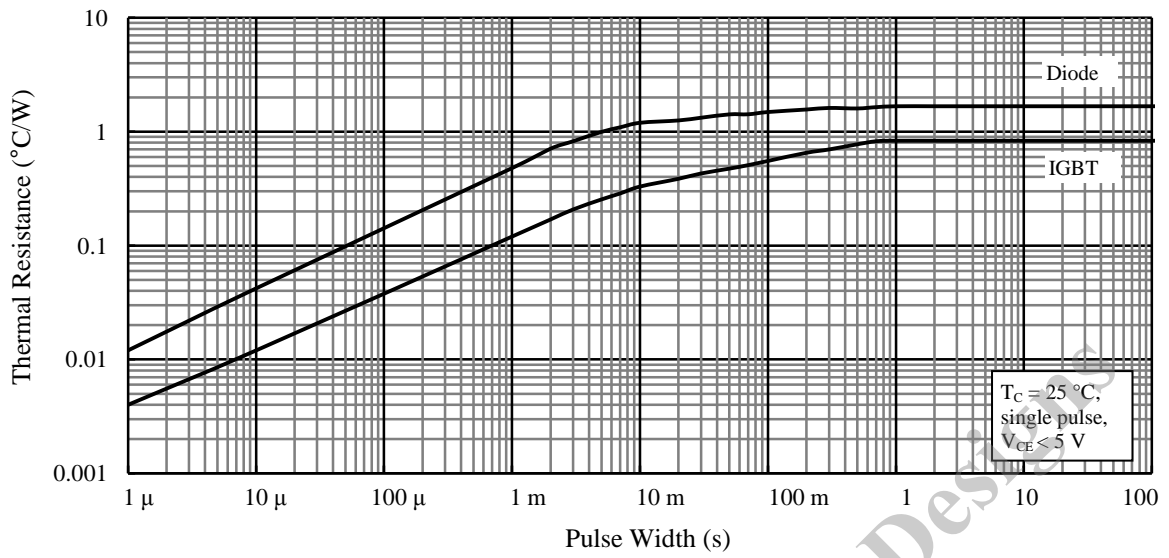


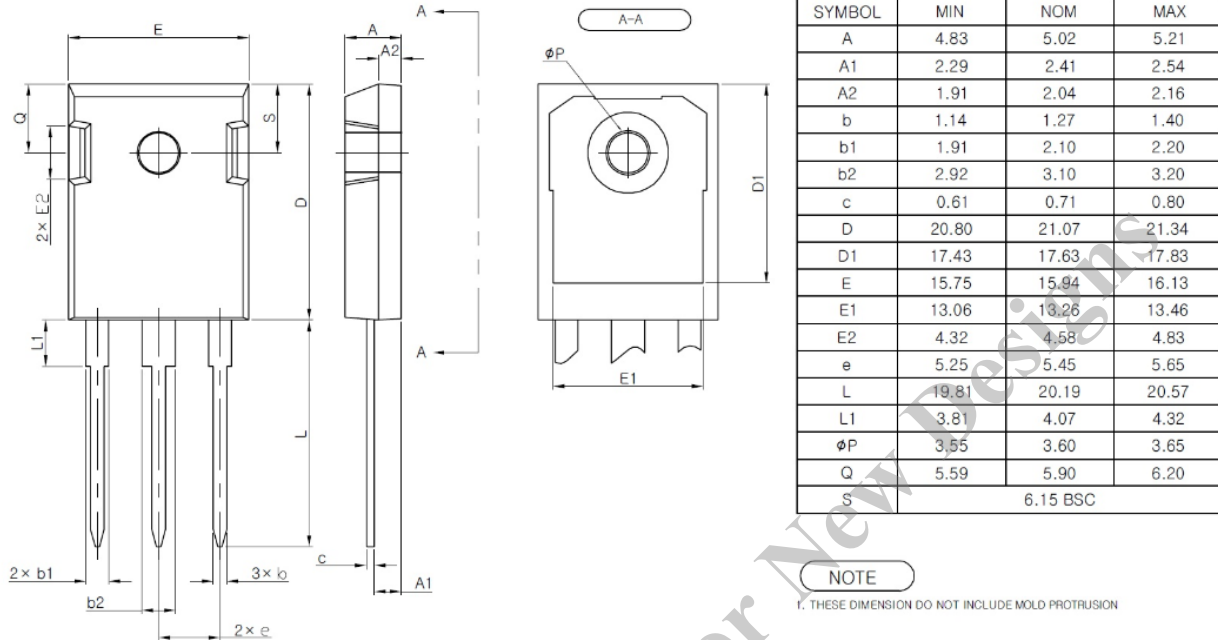
Figure 21. Transient Thermal Resistance

Not Recommended for New Designs

MGD633

Physical Dimension

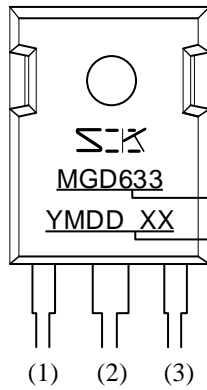
● TO247-3L



NOTES:

- Dimensions in millimeters
- Bare lead frame: Pb-free (RoHS compliant)
- When soldering the products, be sure to minimize the working time within the following limits:
 - Flow: $260 \pm 5 \text{ }^\circ\text{C} / 10 \pm 1 \text{ s}$, 2 times
 - Soldering iron: $380 \pm 10 \text{ }^\circ\text{C} / 3.5 \pm 0.5 \text{ s}$, 1 time (Soldering should be at a distance of at least 1.5 mm from the body of the product.)
- Recommended screw torque: 0.686 N·m to 0.882 N·m (7 kgf·cm to 9 kgf·cm)

Marking Diagram



Part Number

Lot Number

Y is the last digit of the year of manufacture (0 to 9)

M is the month of the year (1 to 9, O, N, or D)

DD is the date of the month (01 to 31)

XX is the control number

Not Recommended for New Designs

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